

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

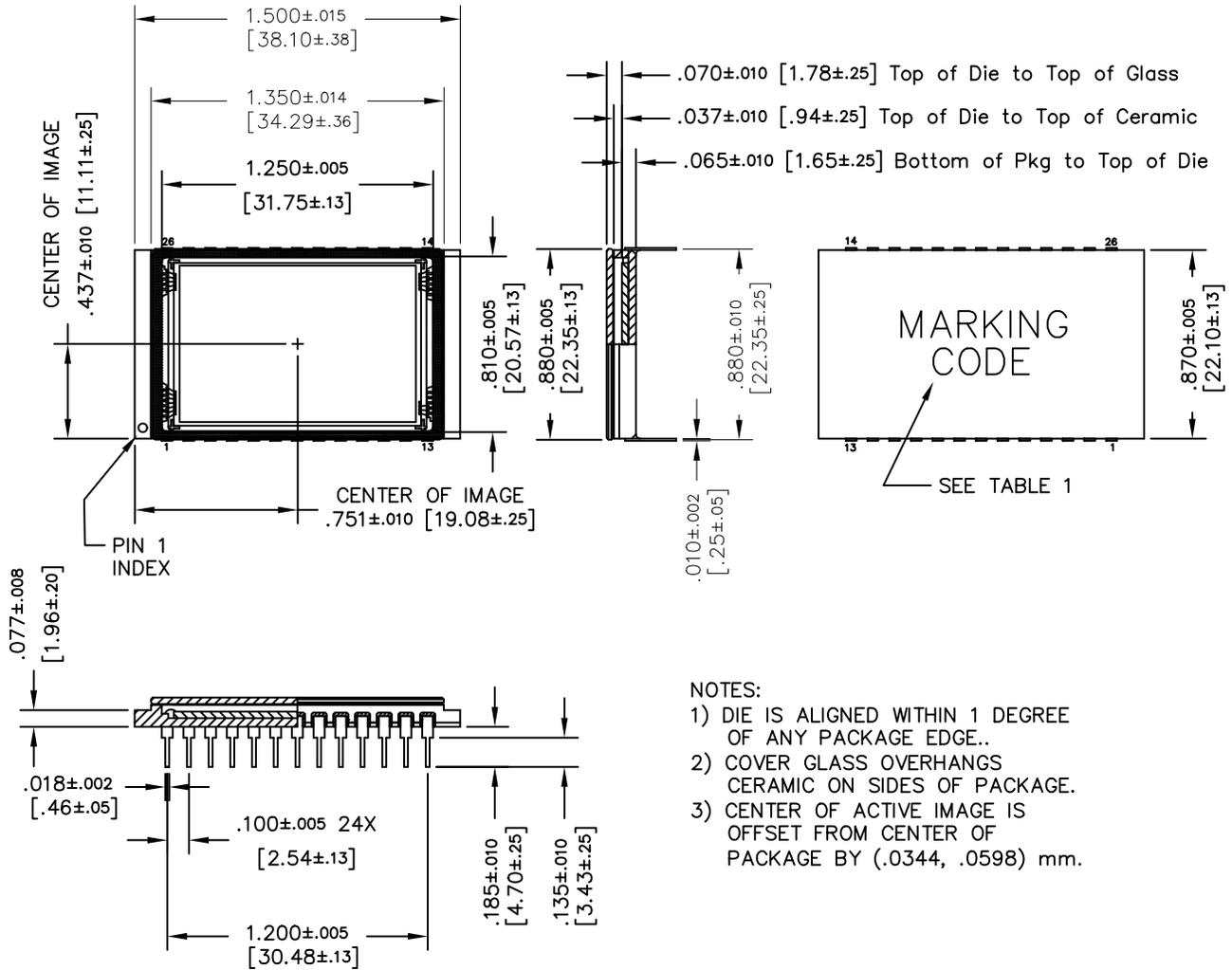
ON Semiconductor®



CERAMIC DIP 26, 38.1x22.61, 2.54P

CASE 125BA
ISSUE O

DATE 30 JUN 2014



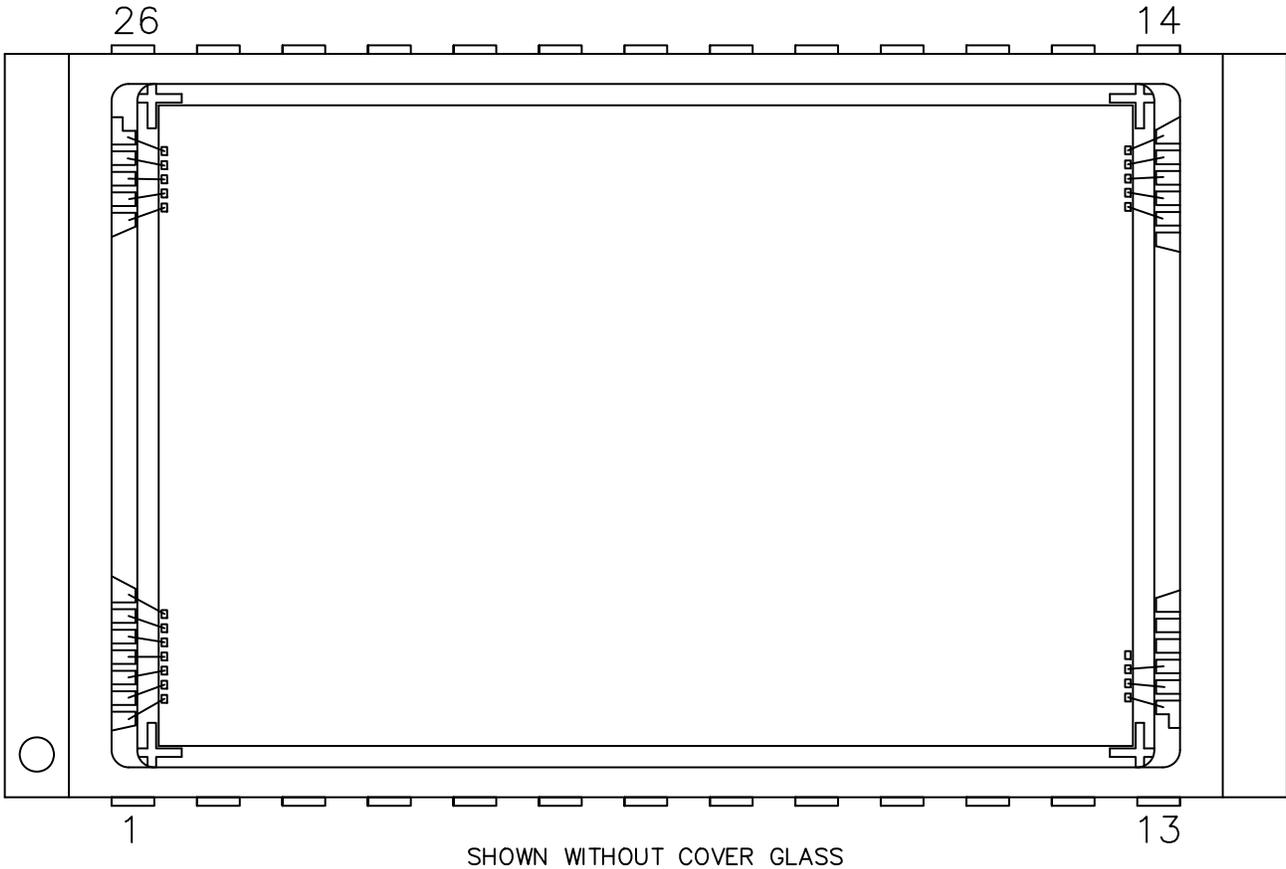
NOTES:

- 1) DIE IS ALIGNED WITHIN 1 DEGREE OF ANY PACKAGE EDGE..
- 2) COVER GLASS OVERHANGS CERAMIC ON SIDES OF PACKAGE.
- 3) CENTER OF ACTIVE IMAGE IS OFFSET FROM CENTER OF PACKAGE BY (.0344, .0598) mm.

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NOTES:

- 1) FOR SINGULATION PURPOSES: DIE ON WAFER ARE STEPPED (x) 29.00 mm, (y) 19.10 mm. ASSUMING 50 MICRON KERF, SINGULATED DIE ARE 28.95 mm X 19.05 mm.
- 2) THERE IS NO INDICATOR ON DIE FOR BOND PAD 1. ORIENT THE CORNER WITH 7 BOND PADS IN THE PIN 1 CORNER OF THE PACKAGE.
- 3) WIRE LOOP HEIGHT: 0.014" +/- .003".

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